



U.S. Ser. No. 10/043,896
Our File: MIT 10523

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Lee et al. **GROUP:** 2871

SERIAL NO: 10/043,896 **EXAMINER:** G.Y. Wang

FILED: January 9, 2002

FOR: HIGH DENSITY INTEGRATED OPTICAL CHIP

**Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

Sir:

RESPONSE

In response to the Office Action mailed November 19, 2003, please amend the above-identified application as follows: